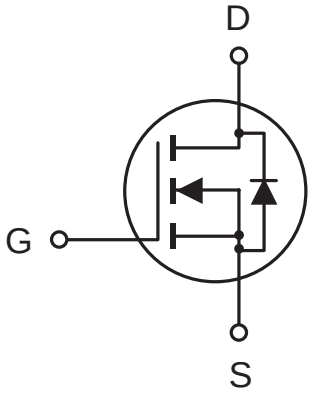
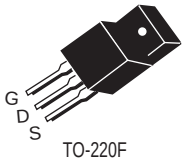
CEFF630

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

- 200V , 7.2A , $R_{DS(ON)}$=300mΩ @V_{GS}=10V
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handling capability.
- TO-220F full-pak for through hole.





ABSOLUTE MAXIMUM RATINGS (Tc=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	200	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	7.2	A
-Pulsed	I_{DM}	24	A
Drain-Source Diode Forward Current	I_S	5.9	A
Maximum Power Dissipation @Tc=25°C Derate above 25°C	P_D	35	W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.6	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	65	°C/W

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ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ[c]	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} = 0V, I_D = 250μA	200			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 200V, V_{GS} = 0V			25	μA
Gate-Body Leakage	I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
ON CHARACTERISTICS[a]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	2		4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 3.5A		270	300	mΩ
On-State Drain Current	$I_{D(ON)}$	V_{GS} = 10V, V_{DS} = 10V	10			A
Forward Transconductance	g_{FS}	V_{DS} = 10V, I_D = 3.5A	3			S
DYNAMIC CHARACTERISTICS[b]						
Input Capacitance	C_{ISS}	V_{DS} = 25V, V_{GS} = 0V f = 1.0MHz		680		pF
Output Capacitance	C_{OSS}			105		pF
Reverse Transfer Capacitance	C_{RSS}			40		pF
SWITCHING CHARACTERISTICS[b]						
Turn-On Delay Time	$t_{D(ON)}$	V_{DD} = 100V, I_D = 5A, V_{GS} = 10V, R_{GEN} = 50Ω		25	60	ns
Rise Time	t_r			75	120	ns
Turn-Off Delay Time	$t_{D(OFF)}$			70	80	ns
Fall time	t_f			35	50	ns
Total Gate Charge	Q_g	V_{DS} = 160V, I_D =5.9A, V_{GS} = 10V		27	33	nC
Gate-Source Charge	Q_{gs}			4		nC
Gate-Drain Charge	Q_{gd}			14		nC

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS [a]						
Diode Forward Voltage	V_{SD}	V_{GS} = 0V, Is =5.9A			1.5	V

Notes

a.Pulse Test:Pulse Width ≤300 μs, Duty Cycle ≤ 2%.

b.Guaranteed by design, not subject to production testing.

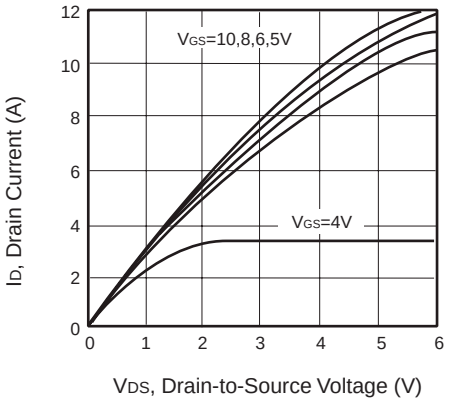

Figure 1. Output Characteristics

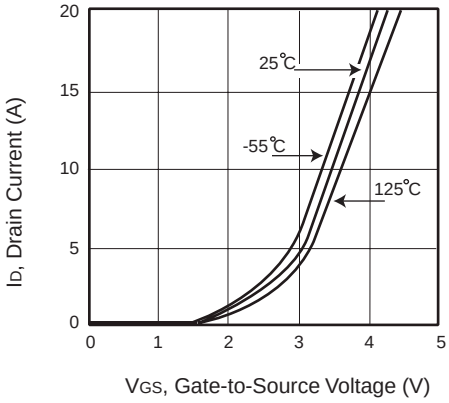

Figure 2. Transfer Characteristics

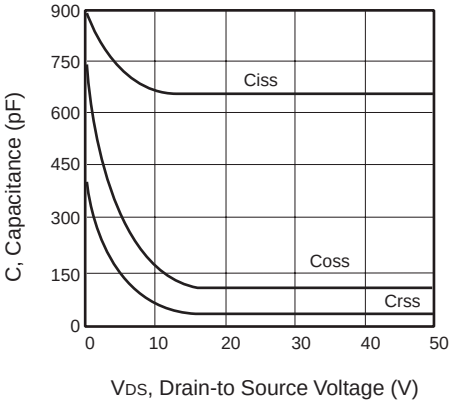

Figure 3. Capacitance

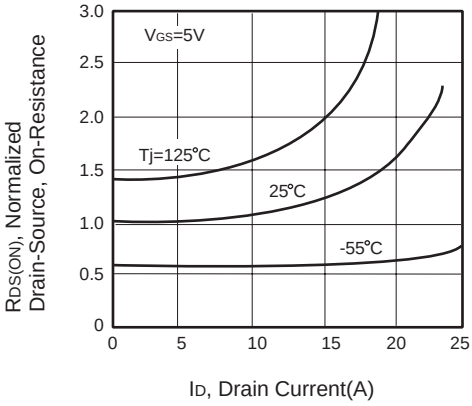

Figure 4. On-Resistance Variation with Drain Current and Temperature

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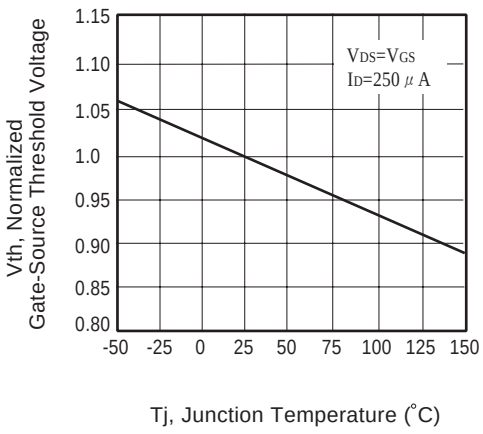

Figure 5. Gate Threshold Variation with Temperature

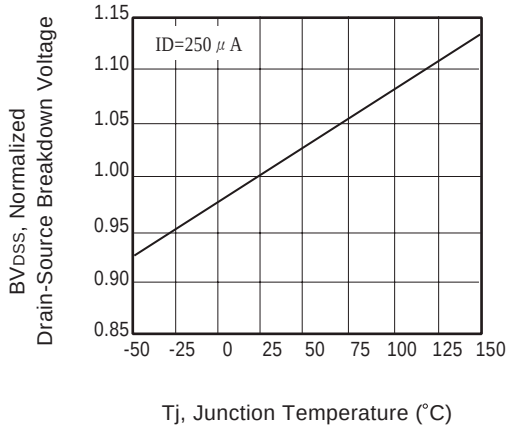

Figure 6. Breakdown Voltage Variation with Temperature

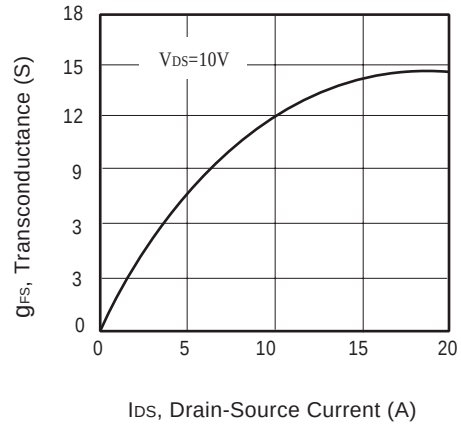

Figure 7. Transconductance Variation with Drain Current

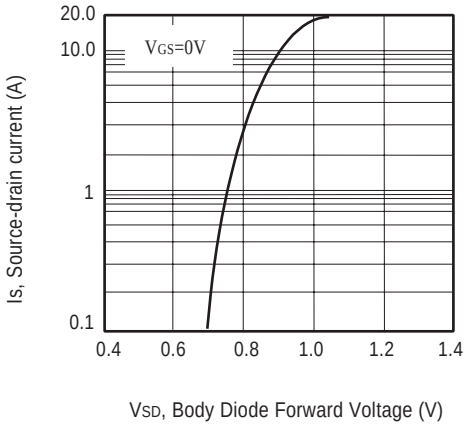

Figure 8. Body Diode Forward Voltage Variation with Source Current

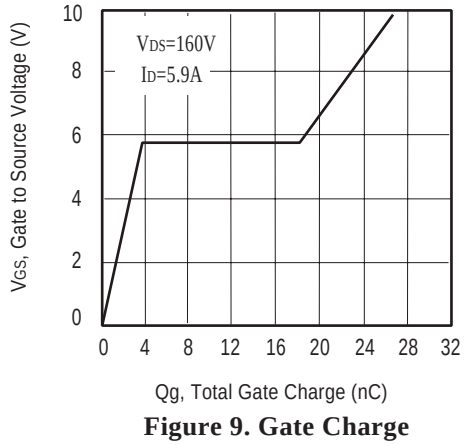

Figure 9. Gate Charge

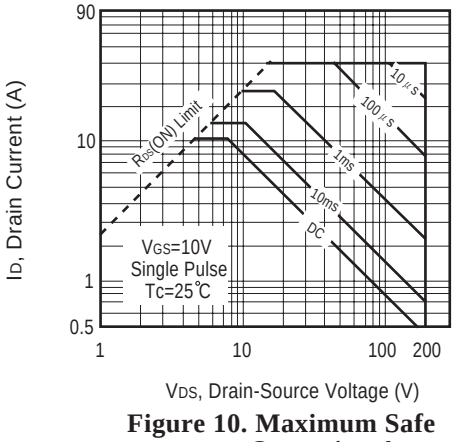

Figure 10. Maximum Safe Operating Area

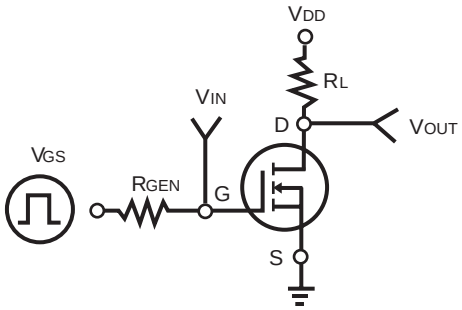

Figure 11. Switching Test Circuit

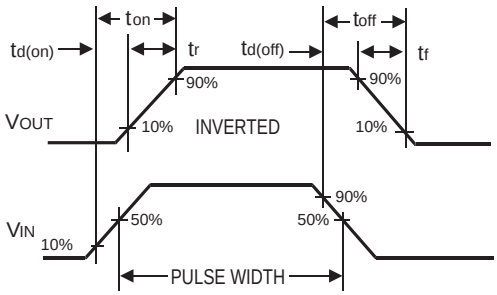

Figure 12. Switching Waveforms

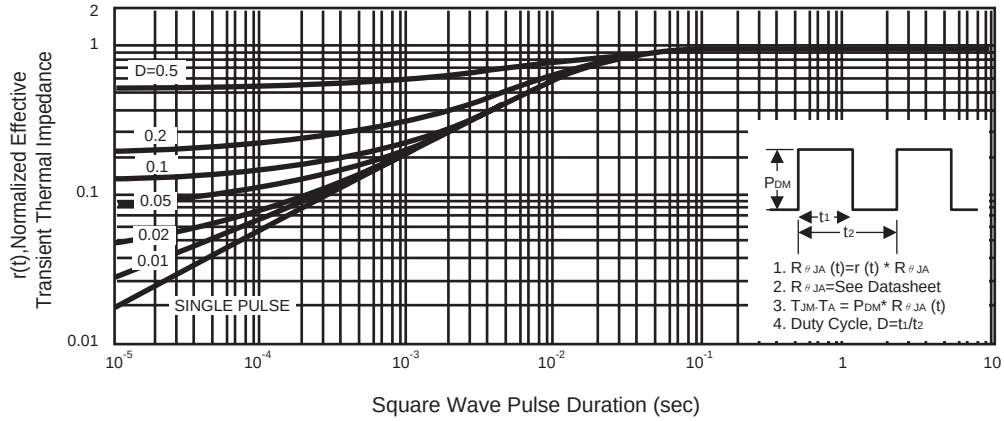

Figure 13. Normalized Thermal Transient Impedance Curve